

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

REISSUE SERIAL NO. :  
FILED :  
GROUP ART UNIT :  
EXAMINER :  
PATENT NO. : 5,397,857  
INVENTORS : Farquhar et al.  
TITLE : "PCMCIA STANDARD MEMORY CARD  
FRAME"

**REISSUE APPLICATION  
INVENTOR'S DECLARATION AND POWER OF ATTORNEY  
KEN DORF**

Assistant Commissioner for Patents  
Box 7  
Washington, D.C. 20231

SIR:

I hereby declare that:

1. My residence, post office address and citizenship are as stated below next to my name.

2. I am a co-inventor for U.S. Patent Application Serial No. 92,012 filed July 15, 1993 and which issued as U.S. Patent No. 5,397,857 on March 14, 1995, and for which invention a reissue patent is being solicited.

3. A copy of the reissue application is attached hereto. I reviewed and understand the contents of the specification, including the claims as amended or added by any amendments specifically referred to herein.

4. I acknowledge the duty to disclose information defined in 37 CFR §1.56 which is material to the examination of this application, namely, information that may affect the patentability of one or more claims in the application.

5. I believe that there is an error in the patent by

reason of my claiming less than I had a right, as one of the patentees, to claim in the patent. I believe the original patent to be partly invalid or inoperative because, erroneously, the patent does not include claims such as the newly amended Claim 1 with Claims 2-8 dependent therefrom and newly added Claims 9-13. This error was made unintentionally and with no intention to deceive or mislead the United States Patent and Trademark Office, and, thus, without deceptive intent.

6. I executed an inventor's oath for a patent application which was filed in the United States Patent and Trademark Office. That application was filed on July 15, 1993 and given U.S. Serial No. 92,012. U.S. Patent No. 5,397,857 issued from that application.

7. During an analysis conducted by counsel for me in January and February, 1997 with respect to the claims of U.S. Patent No. 5,397,857, I was informed that, in counsel's review of the claims as well as art cited during the prosecution of U.S. Patent No. 5,397,857, the invention of U.S. Patent No. 5,397,857 can be distinguished over the art in a number of ways not currently claimed in U.S. Patent No. 5,397,857 and not appreciated during the preparation and filing of the application from which U.S. Patent No. 5,397,857 issued. I am informed that, accordingly, it has been determined that amended original Claim 1 and the newly submitted claims, which are listed in Attachment A hereto, and which do not include certain limitations in the original claim, should be patentable over the prior art, and, therefore, the present reissue application is being filed.

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entitled to claims such as the newly amended Claim 1 with Claims 2-8 dependent therefrom and newly added Claims 9-13.

9. Specifically, Applicants were and are entitled to claims having a breadth as set forth in newly amended Claim 1 and Claims 2-5.

10. Independent Claim 1 of the '857 patent, as amended, recites "A peripheral device PCB package comprising: two stamped metal covers with a plastic frame element corresponding to each cover, each cover having a first side and a second side with a plurality of fingers extending from said sides and wherein edges of the metal covers are bent to conform to the shape of the frame element and said fingers are embedded in the plastic frame elements forming an integral unit, the plastic frame elements being injection molded around the fingers; and wherein the plastic frame element extends beyond a plane of the metal cover so that a plastic perimeter surface is exposed, thereby facilitating bonding of the two covers."

11. Newly added independent Claim 7 recites "A peripheral device PCB package comprising: two stamped metal covers with a plastic frame element corresponding to each cover, each cover having a first side and a second side with a finger extending from one of said sides of each of the covers and wherein edges of the metal covers are bent to conform to the shape of the corresponding frame element and said finger is secured to the plastic frame element forming an integral unit wherein each of the plastic frame elements is injection molded around the finger; and wherein the plastic frame element extends beyond a plane of the metal cover so that a plastic perimeter surface is exposed, thereby facilitating bonding of the two covers."

12. Newly added Claim 8 depends from newly added Claim 7 and recites that the package has a plurality of fingers that extend from one of said sides.

13. Newly added Claim 9 depends from newly added Claim 7 and recites that the package has a plurality of fingers that extend from at least two sides.

14. Newly added Claim 10 depends from newly added Claim 7 and recites that the fingers are embedded in the plastic frame elements.

15. Newly added independent Claim 11 recites a peripheral device PCB package. The package comprises two stamped metal covers having a first side and a second side with a finger extending from one of said sides of each cover. The package further comprises a plastic frame element associated with each of the covers wherein the plastic frame elements are injection molded to secure the finger of each cover to the plastic frame element.

15. Newly added Claim 12 depends from newly added Claim 11 and recites that the package further comprises a plastic perimeter surface extending beyond the plane of the metal cover to facilitate bonding of the two covers.

16. Newly added Claim 13 depends from newly added Claim 12 and recites that each of the plastic perimeter surfaces is integrally formed with the plastic frame elements.

17. Newly added Claim 14 depends from newly added Claim 12 and recites that the plastic perimeter surface is an energy director.

18. Newly added Claim 15 depends from newly added Claim 11 and recites that a finger extends from one of said sides.

19. Newly added Claim 16 depends from newly added Claim 11 and recites that a plurality of fingers extend from at least two sides.

20. Newly added Claim 17 depends from newly added Claim 11 and recites that the edge of the metal cover is bent to conform to the shape of the plastic frame.

21. Newly added independent Claim 18 recites a PCB package comprising: a first package half including a stamped metal cover having an edge formed in a U-shape and a frame element injection molded within the U-shaped edge of the metal cover; a second package half including a stamped metal cover and a molded frame element attached to the metal cover; and the first package half sonically bonded to the second package half.

22. Newly added Claim 19 depends from Claim 18 and recites that the first package half includes a plane bisecting the U-shaped edge at its terminal portion on a first side and a second side of the first package half and a plastic perimeter surface exposed and extending beyond the plane of the first package half to facilitate bonding with the second package half.

23. Newly added Claim 20 depends from newly added Claim 19 and recites that the plastic perimeter surface is an energy director.

24. Newly added Claim 21 depends from newly added Claim 18 and recites that the second package half includes a plane bisecting the U-shaped edge at its terminal portion on a first and a second side of the second package half and a plastic perimeter surface exposed and recessed below the plane of the second package half to facilitate bonding with the first package half.

25. Newly added Claim 22 depends from newly added Claim 18 and recites that the edge is secured to the frame element and the

frame element is injection molded partially around the edge.

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312/876-0200 Ext. 3165

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A Professional Corporation  
85th Floor Sears Tower  
Chicago, Illinois 60606

I hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Co-  
Inventor

KEN DORF

Inventor's Signature

Date: \_\_\_\_\_

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Citizenship

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Full Name of First  
Inventor

James Farquhar

Inventor's Signature

Date: \_\_\_\_\_

Residence

Coronado, CA

Citizenship

UNITED STATES

Post Office Address

44 Port Royale, Coronado, CA

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BRANDT WEIBEZAHN

Inventor's Signature

\_\_\_\_\_  
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6072 Corte Montanas, Pleasanton, Ca  
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11. Newly added independent Claim 7 recites "A peripheral device PCB package comprising: two stamped metal covers with a plastic frame element corresponding to each cover, each cover having a first side and a second side with a finger extending from one of said sides of each of the covers and wherein edges of the metal covers are bent to conform to the shape of the corresponding frame element and said finger is secured to the plastic frame element forming an integral unit wherein each of the plastic frame elements is injection molded around the finger; and wherein the plastic frame element extends beyond a plane of the metal cover so that a plastic perimeter surface is exposed, thereby facilitating bonding of the two covers."



12. Newly added Claim 8 depends from newly added Claim 7 and recites that the package has a plurality of fingers that extend from one of said sides.

13. Newly added Claim 9 depends from newly added Claim 7 and recites that the package has a plurality of fingers that extend from at least two sides.

14. Newly added Claim 10 depends from newly added Claim 7 and recites that the fingers are embedded in the plastic frame elements.

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15. Newly added Claim 12 depends from newly added Claim 11 and recites that the package further comprises a plastic perimeter surface extending beyond the plane of the metal cover to facilitate bonding of the two covers.

16. Newly added Claim 13 depends from newly added Claim 12 and recites that each of the plastic perimeter surfaces is integrally formed with the plastic frame elements.

17. Newly added Claim 14 depends from newly added Claim 12 and recites that the plastic perimeter surface is an energy director.

18. Newly added Claim 15 depends from newly added Claim 11 and recites that a finger extends from one of said sides.

19. Newly added Claim 16 depends from newly added Claim 11 and recites that a plurality of fingers extend from at least two sides.

20. Newly added Claim 17 depends from newly added Claim 11 and recites that the edge of the metal cover is bent to conform to the shape of the plastic frame.

21. Newly added independent Claim 18 recites a PCB package comprising: a first package half including a stamped metal cover having an edge formed in a U-shape and a frame element injection molded within the U-shaped edge of the metal cover; a second package half including a stamped metal cover and a molded frame element attached to the metal cover; and the first package half sonically bonded to the second package half.

22. Newly added Claim 19 depends from Claim 18 and recites that the first package half includes a plane bisecting the U-shaped edge at its terminal portion on a first side and a second side of the first package half and a plastic perimeter surface exposed and extending beyond the plane of the first package half to facilitate bonding with the second package half.

23. Newly added Claim 20 depends from newly added Claim 19 and recites that the plastic perimeter surface is an energy director.

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312/876-0200 Ext. 3165

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A Professional Corporation  
85th Floor Sears Tower  
Chicago, Illinois 60606

I hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Co-  
Inventor

IGGONI FAJARDO

Inventor's Signature

Date: \_\_\_\_\_

Residence

San Jose, CA

Citizenship

PHILIPPINES

Post Office Address

1447 Maxwell Way, San Jose, CA 95131

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

REISSUE SERIAL NO. :  
FILED :  
GROUP ART UNIT :  
EXAMINER :  
PATENT NO. : 5,397,857  
INVENTORS : Farquhar et al.  
TITLE : "PCMCIA STANDARD MEMORY CARD  
FRAME"

**REISSUE APPLICATION  
INVENTOR'S DECLARATION AND POWER OF ATTORNEY  
CHARLES CENTOFANTE**

Assistant Commissioner for Patents  
Box 7  
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Full Name of Co-  
Inventor

CHARLES CENTOFANTE

Inventor's Signature

\_\_\_\_\_  
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Residence

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USA

Post Office Address

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REISSUE SERIAL NO. : 08/818,520  
FILED : March 14, 1997  
GROUP ART UNIT : 2109  
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INVENTOR'S DECLARATION AND POWER OF ATTORNEY  
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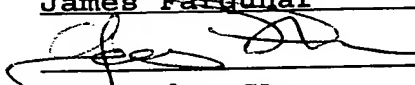
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Full Name of First  
Inventor

James Parguhar

Inventor's Signature  
Residence  
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Post Office Address

 Date: 6/11/98  
Coronado, CA  
UNITED STATES  
44 Port Royale, Coronado, CA

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11. Newly added independent Claim 7 recites "A peripheral device PCB package comprising: two stamped metal covers with a plastic frame element corresponding to each cover, each cover

having a first side and a second side with a finger extending from one of said sides of each of the covers and wherein edges of the metal covers are bent to conform to the shape of the corresponding frame element and said finger is secured to the plastic frame element forming an integral unit wherein each of the plastic frame elements is injection molded around the finger; and wherein the plastic frame element extends beyond a plane of the metal cover so that a plastic perimeter surface is exposed, thereby facilitating bonding of the two covers.

12. Newly added Claim 8 depends from newly added Claim 7 and recites that the package has a plurality of fingers that extend from one of said sides.

13. Newly added Claim 9 depends from newly added Claim 7 and recites that the package has a plurality of fingers that extend from at least two sides.

14. Newly added Claim 10 depends from newly added Claim 7 and recites that the fingers are embedded in the plastic frame elements.

15. Newly added independent Claim 11 recites a peripheral device PCB package. The package comprises two stamped metal covers having a first side and a second side with a finger extending from one of said sides of each cover. The package further comprises a plastic frame element associated with each of the covers wherein the plastic frame elements are injection molded to secure the finger of each cover to the plastic frame element.

15. Newly added Claim 12 depends from newly added Claim 11 and recites that the package further comprises a plastic perimeter surface extending beyond the plane of the metal cover to facilitate bonding of the two covers.

16. Newly added Claim 13 depends from newly added Claim 12 and recites that each of the plastic perimeter surfaces is integrally formed with the plastic frame elements.

17. Newly added Claim 14 depends from newly added Claim 12 and recites that the plastic perimeter surface is an energy director.

18. Newly added Claim 15 depends from newly added Claim 11 and recites that a finger extends from one of said sides.

19. Newly added Claim 16 depends from newly added Claim 11 and recites a plurality of fingers extending from at least two sides.

20. Newly added Claim 17 depends from newly added Claim 11 and recites that the edge of the metal cover is bent to conform to the shape of the plastic frame.

21. Newly added independent Claim 18 recites a PCB package comprising: a first package half including a stamped metal cover having an edge formed in a U-shape and a frame element injection molded within the U-shaped edge of the metal cover; a second package half including a stamped metal cover and a molded frame element attached to the metal cover; and the first package half sonically bonded to the second package half.

22. Newly added Claim 19 depends from Claim 18 and recites



that the first package half includes a plane bisecting the U-shaped edge at its terminal portion on a first side and a second side of the first package half and a plastic perimeter surface exposed and extending beyond the plane of the first package half to facilitate bonding with the second package half.

23. Newly added Claim 20 depends from newly added Claim 19 and recites that the plastic perimeter surface is an energy director.

24. Newly added Claim 21 depends from newly added Claim 18 and recites that the second package half includes a plane bisecting the U-shaped edge at its terminal portion on a first and a second side of the second package half and a plastic perimeter surface exposed and recessed below the plane of the second package half to facilitate bonding with the first package half.

25. Newly added Claim 22 depends from newly added Claim 18 and recites the edge is secured to the frame element and the frame element is injection molded partially around the edge.

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A Professional Corporation  
85th Floor Sears Tower  
Chicago, Illinois 60606

I hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Co-  
Inventor

KEN DORF

Inventor's Signature  
Residence  
Citizenship  
Post Office Address



Date: 7/7/98

San Jose, CA

UNITED STATES

1376 Camino Robles Way, San Jose, CA  
95120

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

REISSUE SERIAL NO. : 08/818,520  
FILED : March 14, 1997  
GROUP ART UNIT : 2109  
EXAMINER :  
PATENT NO. : 5,397,857  
INVENTORS : Farquhar et al.  
TITLE : "PCMCIA STANDARD MEMORY CARD  
FRAME"

**REISSUE APPLICATION  
INVENTOR'S DECLARATION AND POWER OF ATTORNEY  
BRANDT WEIBEZAHN**

Assistant Commissioner for Patents  
Box 7  
Washington, D.C. 20231

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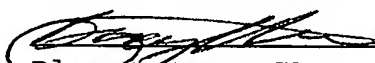
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Full Name of Co-  
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BRANDT WEIBEZAHN

Inventor's Signature



Date: 6/12/98

Residence

Pleasanton, CA

Citizenship

UNITED STATES

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13. Newly added Claim 9 depends from newly added Claim 7 and recites that the package has a plurality of fingers that extend from at least two sides.

14. Newly added Claim 10 depends from newly added Claim 7 and recites that the fingers are embedded in the plastic frame elements.

15. Newly added independent Claim 11 recites a peripheral device PCB package. The package comprises two stamped metal covers having a first side and a second side with a finger extending from one of said sides of each cover. The packages further comprises a plastic frame element associated with each of the covers wherein the plastic frame elements are injection molded to secure the finger of each cover to the plastic frame element.

15. Newly added Claim 12 depends from newly added Claim 11 and recites a package that further comprises a plastic perimeter surface extending beyond the plane of the metal cover to facilitate bonding of the two covers.

16. Newly added Claim 13 depends from newly added Claim 12 and recites a package wherein each of the plastic perimeter surfaces is integrally formed with the plastic frame elements.

17. Newly added Claim 14 depends from newly added Claim 12 and recites that the plastic perimeter surface is an energy director.

18. Newly added Claim 15 depends from newly added Claim 11 and recites that a finger extends from one of said sides.

19. Newly added Claim 16 depends from newly added Claim 11 and recites a plurality of fingers extending from at least two sides.

20. Newly added independent Claim 18 recites a PCB package comprising: a first package half including a stamped metal cover having an edge formed in a U-shape and a frame element injection molded within the U-shaped edge of the metal cover; a second package half including a stamped metal cover and a molded frame element attached to the metal cover; and the first package half sonically bonded to the second package half.

21. Newly added Claim 19 depends from Claim 18 and recites that the first package half includes a plane bisecting the U-shaped edge at its terminal portion on a first side and a second side of the first package half and a plastic perimeter surface



exposed and extending beyond the plane of the first package half to facilitate bonding with the second package half.

22. Newly added Claim 20 depends from newly added Claim 19 and recites that the plastic perimeter surface is an energy director.

23. Newly added Claim 21 depends from newly added Claim 18 and recites that the second package half includes a plane bisecting the U-shaped edge at its terminal portion on a first and a second side of the second package half and a plastic perimeter surface exposed and recessed below the plane of the second package half to facilitate bonding with the first package half.

24. Newly added Claim 22 depends from newly added Claim 18 and recites the edge is secured to the frame element and the frame element is injection molded partially around the edge.

25. Newly added Claim 23 depends from newly added Claim 18 and recites that a finger extends at an angle from the edge of the metal cover and the finger having the frame element partially injection molded around the finger.

26. The package as claimed in Claim 18 wherein the first package half includes a plane bisecting the U-shaped edge at its terminal portion on a first side and a second side of the first package half and a plastic perimeter surface exposed and extending beyond the plane of the first package half to facilitate bonding with the second package half.

27. It was my unintended mistake in the independent claim

as originally filed with the application that the claim could be effectively written to read on the preferred embodiments of my invention in which a finger extends from each of the metal covers wherein each finger is secured to a plastic frame element by injection molding of the plastic frame element around the finger. Therefore, the newly presented claims define an invention disclosed by my original specification and not taught by any reference or combination of references of which I am aware.

28. The error in the originally filed claim which issued on a second Office Action by the U.S. Patent Office arose without any deceptive intention on my part.

A copy of the reissue application is attached hereto. I have reviewed and understand the contents of the specification, including the claims, as amended or added by any amendments specifically referred to herein.

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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I hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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